

# **AUIR3200S**

## MOSFET DRIVER WITH PROTECTION AND DIAGNOSTIC

#### **Features**

- Bootstrap and charge pump
- Over temperature shutdown (with Ptc interface)
- Short circuit protection (Vds detection)
- Reverse battery protection (turns On the MOSFET)
- Diagnostic
- ESD protection

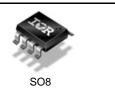
#### **Description**

The AUIR3200S is a high side mosfet driver for very low Rdson automotive application. It offers over-current, over-temperature protection and diagnostic. The over-current protection is done by monitoring the Vds voltage, the threshold is programmable by external resistor. The over-temperature protection uses a thermal sensor. The AUIR3200S offers diagnostic on the input pin.

## **Product Summary**

Operating voltage 6-36V Vgate 6V

#### **Package**



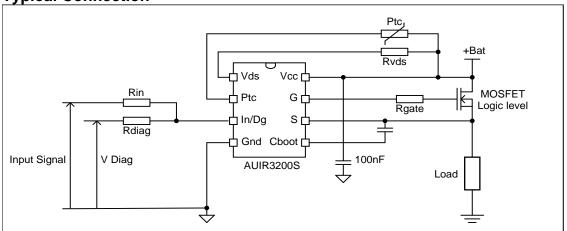
#### **Ordering Information**

Base Part Number		Standard Pack	Olete Best Nesseles	
Base Fait Number	Package Type	Form	Quantity	Complete Part Number
AUIR3200S	SOIC-8 leads	Tube	95	AUIR3200S
AUIK32003	SOIC-6 leads	Tape and Reel	2500	AUIR3200STR

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**Typical Connection** 



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## **Absolute Maximum Ratings**

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are referenced to Ground lead. (Tj= -40°C..150°C unless otherwise specified).

Symbol	Parameter	Min.	Max.	Units
Vcc-gnd	Maximum Vcc voltage	-0.3	60	
Vcc-Vds	Maximum Vds pin voltage	-0.3	5.5	
Vcc-Vptc	Maximum Ptc pin voltage	-0.3	5.5	
Vin-gnd	Maximum IN pin voltage	-0.3	5.5	V
Vcc-Vs	Maximum S pin voltage	-0.3	60	
Vcboot-Vs	Maximum Cboot pin voltage	-0.3	8	
Vcc cont.	Maximum continuous Vcc voltage	_	36	
Tj max.	Maximum operating junction temperature	-40	150	
ijillax.	Maximum storage temperature	-55	150	°C
Tsoldering	Soldering temperature (10 seconds)	_	300	

#### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
Rth	Thermal resistance junction to ambient	100		°C/W

**Recommended Operating Conditions** 

Symbol	Parameter	Min.	Max.	Units
VIH	High level input voltage	2.7	5.5	W
VIL	Low level input voltage	0	0.9	v
Rin	Recommended resistor in series with IN pin	10	15	VO.
Rdiag	Recommended resistor in series with Diag pin	4	15	ΚΩ

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#### **Static Electrical Characteristics**

Tj=-40°C..125°C, Vcc=6-36V (unless otherwise specified), typical value are given for Vcc=14V and Tj=25°C.

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Vcc op.	Operating voltage range	6	_	36	V	
Icc Off	Supply current in sleep mode Tj=25°C	_	1	5	μΑ	Vcc=14V, Vin=0V
Icc On	Supply current when On		10	15	mA	Vin=5V, Vptc=Vbat, Vds=Vbat
VIH	IN High threshold voltage	_	2	2.6		
VIL	IN Low threshold voltage	0.5	1.7	2.1	V	
In hyst.	Input hysteresis	0.2	0.5	1		
lin on	On state input current	_	33	50	μΑ	Vin=5V
Vgs	Gate output voltage	5	5.7	_		Igs=0μA
Vgs rev	Gate output voltage during reverse battery Tj=25°C	4.5	5.6	_	V	Igs=50μA, Vbat=14V
Vin, off	Input voltage when the part is in fault mode		0.25	0.4		ldg=300μA

#### **Protection Characteristics**

Tj=-40°C..125°C, Vcc=6-36V (unless otherwise specified), typical value are given for Vcc=14V and Tj=25°C.

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
lvds	Vds current reference	0.7	0.8	0.91		Vcc-Vds=0V, Tj=-40°C
		0.84	0.93	1.05	mA	Vcc-Vds=0V, Tj=25°C
		1	1.15	1.33		Vcc-Vds=0V, Tj=125°C
Vds offset	Vds comparator offset	-10	0	10	mV	
Tblank on	Vds detection blanking time during turn on	15	22	35	μs	
Vptc	PTC comparator voltage threshold (Vcc-Vptc)	1.5	2	2.5	V	Vin=5V, Vcc=14V
Rptc	Pull down resistor on the PTC pin	4	10	20	kΩ	
Tdiag	Diagnostic time	_	10	_		see figure 2
Tsleep	Time to enter in sleep mode	7	15	30	ms	see figure 2
Treset	Time to enter in sleep mode and reset the fault	_	5	_	1115	see figure 2
Twkp	Time to leave the sleep mode	0.5	_	_	μs	Rin=10k see figure 3 & 4
Tpwr on rst	Power on reset duration Tj=25°C	40	100	200	μs	
ÚV	Under voltage threshold		5.2	5.9	V	
T UV hold	Time to keep UV detection active	150	350	600	μs	



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**Switching Characteristics**Tj=-40..125°C, Vcc=6..36V (unless otherwise specified), typical value are given for Vcc=14V and Tj=25°C.

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Tdon	Turn-on delay to 20% of Vgs	_	1.6	_		Qg=220nc,
Tr	Rise time 20% to 80% of Vgs	_	1	_		Rgate=0Ω
Tdoff	Turn off delay time to 80% of Vgs	_	2	_	μs	
Tf	Fall time from 80% to 20% of Vgs	_	1	_		
lgs+	Gate output high pulsed current	100	160	_	mA	Vgs=0V
lgs-	Gate output low pulsed current	100	130	_	IIIA	Vgs=5.7V
lboot	Cboot capacitor charge current	0.35	0.8	_	Α	
Vboot-Source	Cboot capacitor charge voltage	5.6	6	_	V	

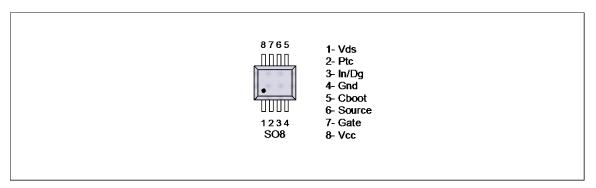
#### **True Table**

Operating Conditions	IN	OUT	DG
Normal ON	Н	Н	Н
Normal OFF	L	L	L
Short circuit to Gnd	Н	L	L
Short circuit to Gnd	L	L	L
Over-temperature	Н	L	L
Over-temperature	L	L	L

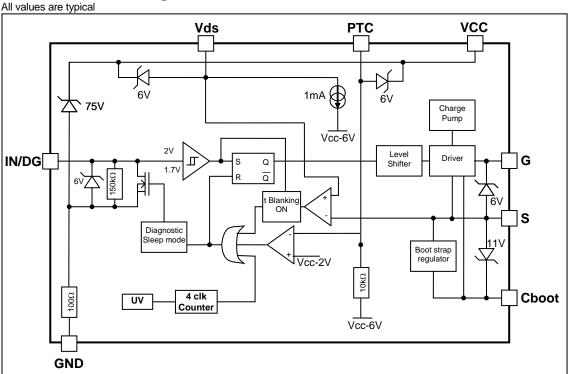
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## **Lead Assignments**



## **Functional Block Diagram**





#### **Over-current protection**

The over-current protection is done by monitoring the Vds voltage of the Mosfet. The threshold is adjusted by connecting the appropriate resistor between Vcc and Vds pin. Below the formula to set the appropriate over-current threshold:

$$Isd\_threshold = \frac{Ivds \times Rvds}{RdsOn}$$

The Ivds has a positive temperature coefficient to compensate the positive temperature coefficient of the Rdson of the Mosfet.

The above formula is only valid when the Mosfet is fully ON. Therefore during the turn on of the MOSFET, the time 'Tblank on' disable the vds protection until the Mosfet is fully On.

#### Over-temperature protection

The temperature protection uses a PTC sensor connected to the tab or the drain of the Mosfet depending on the mounting. The purpose is to maximize the thermal interface between the sensor and the junction. The PTC sensor, the Vds threshold and the Mosfet must be chosen in order to not exceed the maximum junction temperature of the Mosfet during a short circuit.

Protection is evaluated by switching the Mosfet on different currents and by evaluating the junction temperature when the Mosfet is switched off by the protections. This gives the following drawing. For high impedance short circuit, Vds is smaller than Vds threshold, so the over-temperature will act. For low impedance short circuit, the Vds protection will switch off the Mosfet. At the transition current between the 2 protections the junction temperature of the Mosfet is the maximum and should be lower than the maximum rating.

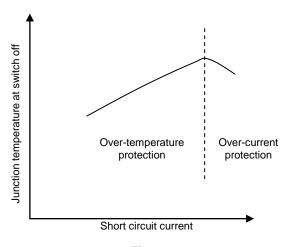


Figure 1



#### Sleep\_mode / Diagnostic

Sleep\_mode block manages the diagnostic and the sleep\_mode. The device enters in sleep mode if input is inactive during a delay higher than Tsleep.

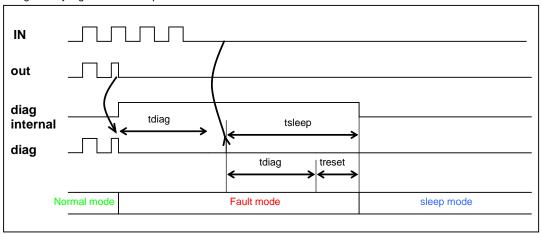


Figure 2

### Wake up sequence

To wake up the part from the sleep mode, the input must be activated at least during Twkp, then the bootstrap regulator is switched on and the bootstrap capacitor is charged. The output will not be activated during Tpw on rst.

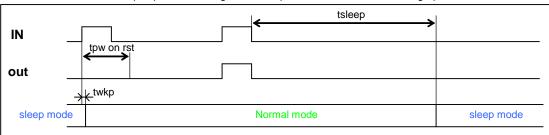


Figure 3

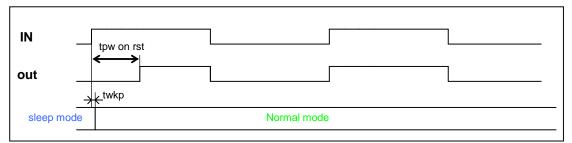


Figure 4



#### **Bootstrap**

The bootstrap capacitor provides the necessary current to the driver in order to charge the gate capacitor to the right voltage level.

A design rule to select the bootstrap capacitor value is to choose 10 times the gate capacitance.

You can find in the Mosfet datasheet 'Qg max' for a specific Vgs.

Use this equation to calculate Cboot value:

$$Cboot = 10 \times \frac{Qg \max}{Vgs}$$

The AUIR3200S integrates a bootstrap regulator to maintain a fixed voltage (Vboot=6V) on the bootstrap capacitor for any battery voltage.

The regulator is off during the sleep mode to reduce the current consumption.

The power on reset is necessary to charge the bootstrap capacitor before turns on the power mosfet. The bootstrap capacitor gets its charge through the load. So the time to charge it depends of the load.

But the power on reset doesn't monitor the bootstrap capacitor voltage. Its time is set internally to allow starting the most of load without implement a special sequence:

The power on reset is long enough to charge the bootstrap capacitor before turns on the power mosfet.

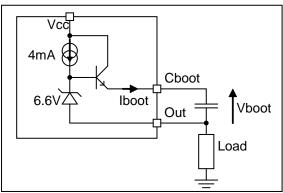


Figure 5

Time to charge the bootstrap capacitor

Power on reset time

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If the inductance of the load is too important, the power on reset is not enough long to charge completely the bootstrap capacitor before turns on the power mosfet.

So the micro-processor need to implement a special sequence to start the device without activates the output power mosfet.

The micro-processor send one short pulse (Twkp min < short pulse < Tpwr\_on\_rst) then wait for the bootstrap capacitor is totally charged and after provide the appropriate duty cycle.

The bootstrap charge depends of the battery voltage, the bootstrap capacitor value and the inductance load value.

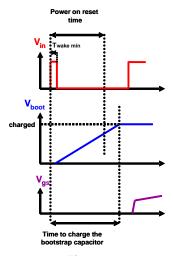


Figure 7



#### IN frequency and duty cycle

The Vds protection is not active if the time ON is lower than Tblank on. So the minimum time ON (ton) is 'Tblank on max' to be sure that this protection will be active.

The times OFF (toff) needs to be setup for assure that the capacitor bootstrap will be recharged up to 6V. The bootstrap time charge depends of the bootstrap capacitor value and the inductance load value.

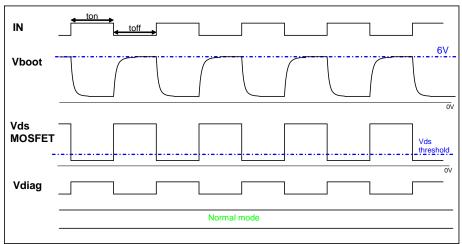


Figure 8

If the capacitor is discharged at the turn ON of the MOSFET, the AUIR3200S will detect a fault (VDS protection) after Tblank ON because the MOSFET won't be fully ON.

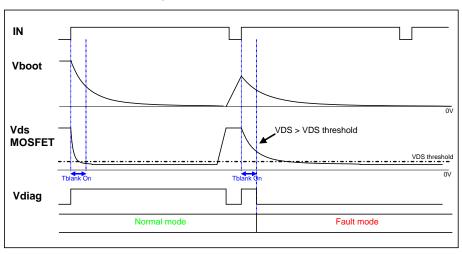


Figure 9



### Under voltage protection in short-circuit mode

During short circuit condition, it may happen that the supply voltage drops below the under voltage before the short is detected by the Vds protection due to the blanking time 'Tblank on'.

In under voltage condition the AUIR3200S turns off the MOSFET. The time 'Tblank On' is reset.

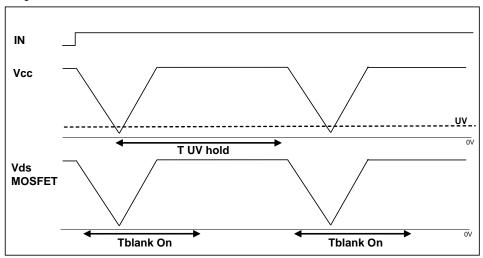


Figure 10

In order to detect the short circuit condition, the AUIR3200S has a counter and after 4 'under voltage' detections, the part is latched and the fault diagnostic is activated. The counter is reset when the part goes to sleep mode.

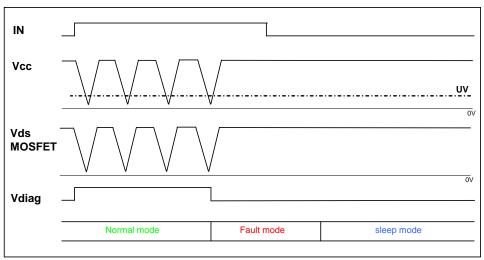


Figure 11



#### PWM operation (Ton<Tblank on)

PWM operation is also possible. The boostrap feature allows fast switching. When the Ton is shorter than the Tblank On, the Vds protection is no longer activated. In order to protect the Power Mosfet, the AUIR3200S integrates a counter which is incremented by the input signal and reset when the Vds voltage is below the Vds threshold. The counter latches off the AUIR3200S after 4 activations. During PWM operation (Ton< Tblank On) on a short circuit, the Vds is always above the Vds threshold and 4 activations on the input will latch the AUIR3200S and the fault diagnostic is activated.

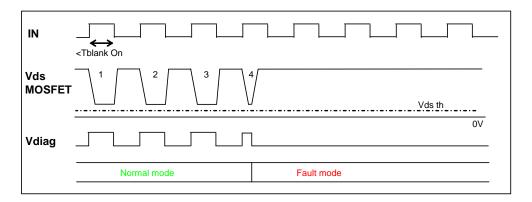
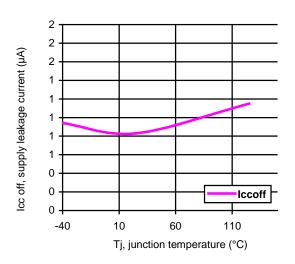


Figure 12



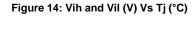
## Parameters curves: typical value



3 2 1 VIH -VIL -25 -50 0 50 75 100 125 150 Tj, junction temperature (°C)

Vih and Vil (V)

Figure 13: Icc off (µA) Vs Tj (°C) Vcc=14V,Vin=0V)



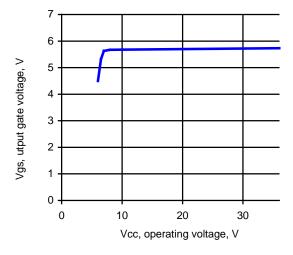


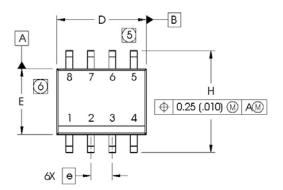
Figure 15: Vgs vs Vcc with Ivgs=50µA

MILLIMETERS



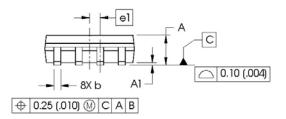
#### Case Outline - SO8

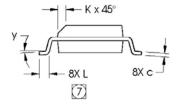
Dimensions are shown in millimeters (inches)



DIM			4			
DilVi	MIN	MAX	MIN	MAX		
Α	.0532	.0688	1.35	1.75		
A1	.0040	.0098	0.10	0.25		
b	.013	.020	0.33	0.51		
О	.0075	.0098	0.19	0.25		
D	.189	.1968	4.80	5.00		
Е	.1497	.1574	3.80	4.00		
е	.050 B	ASIC	1.27 BASIC			
e1	.025 B	ASIC	0.635 BASIC			
Н	.2284	.2440	5.80	6.20		
K	.0099	.0196	0.25	0.50		
L	.016	.050	0.40	1.27		
У	0°	8°	0°	8°		

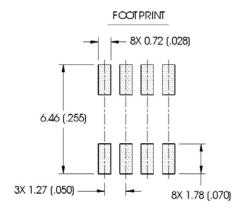
INCHES





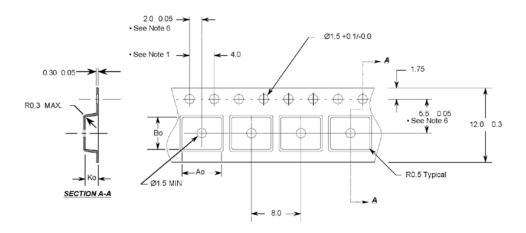
#### NOTES:

- 1. DIMENSIONING & TOLERANGING PER ASME Y14.5M-1994.
- 2. CONTROLLING DIMENSION: MILLIMETER
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
- 4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- (5) DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
- (6) DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
- (7) DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.



#### Tape & Reel **SO8**





#### Notes:

- 1. 10 sprocket hole pitch cumulative tolerance 0.2
- Camber not to exceed 1 mm in 100mm
   Material: Black Conductive Advantek Polystyrene
   Ao and Bo measured on a plane 0.3mm above the
- bottom of the pocket
- 5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- 6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

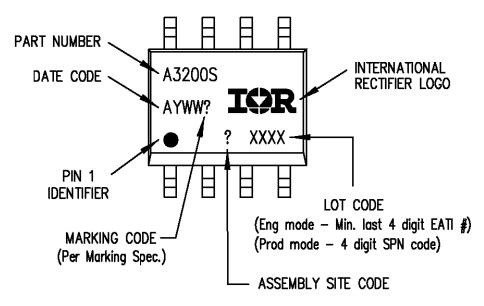
Ao = 6.4 mm Bo = 5.2 mm

Ko = 2.1 mm

- All Dimensions in Millimeters -



## **Part Marking Information**



TOP MARKING (LASER)

### Qualification Information<sup>†</sup>

<u> wuaiiiiu</u>	auon iniormation					
Qualification Level		(p	Automotive (per AEC-Q100)  Comments: This family of ICs has passed an Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
		Industrial and Consumer qualification				
Moisture Sensitivity Level		SOIC8N	MSL2 260°C (per IPC/JEDEC J-STD-020)			
	Machine Model		SS M1B(+/-100V) AEC-Q100-003)			
ESD	Human Body Model	Class H1C (+/-1500V) (per AEC-Q100-002)				
Charged Device Model		Class C4 (+/-1000V) (per AEC-Q100-011)				
IC Latch-Up Test			ass II, Level A AEC-Q100-004)			
RoHS Compliant		Yes				

† Qualification standards can be found at International Rectifier's web site http://www.irf.com/



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#### **WORLD HEADQUARTERS:**

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**Revision History** 

Revision	Date	Notes/Changes
Α	November 2, 2012	Initial release